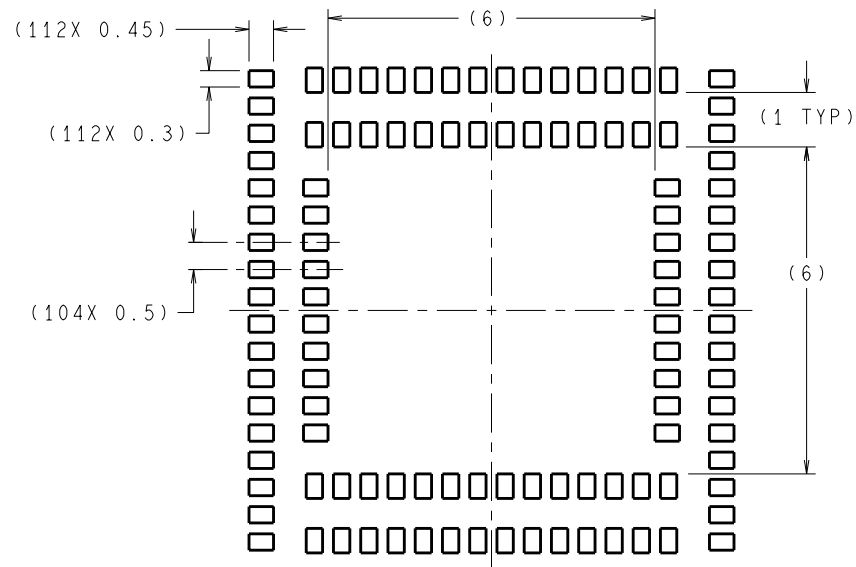
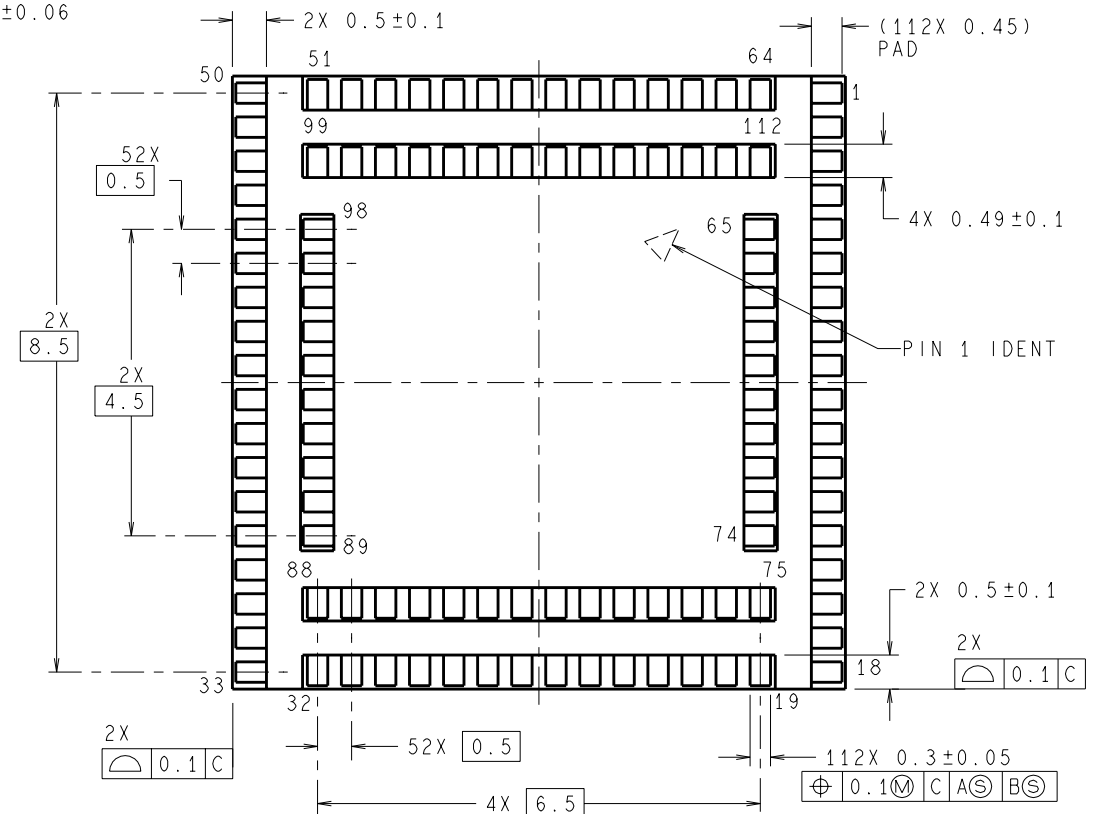
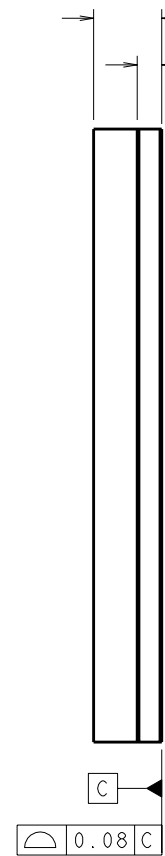
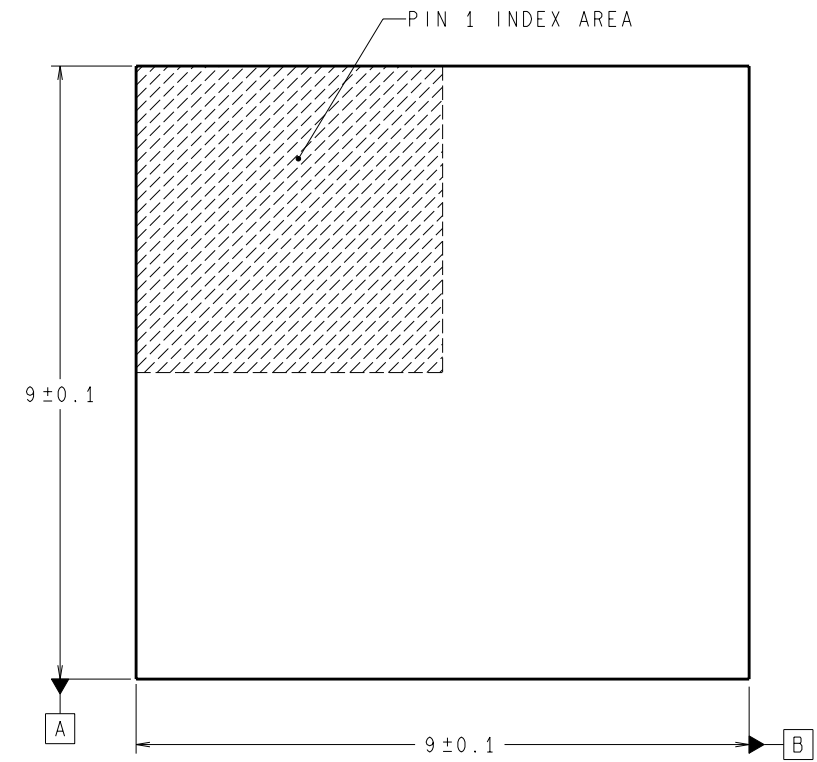


REVISIONS				
LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL	12335	01/27/2000	TL/GN



**RECOMMENDED LAND PATTERN**  
1:1 RATIO WITH PACKAGE SOLDER PADS

DIMENSIONS ARE IN MILLIMETERS



- NOTES: UNLESS OTHERWISE SPECIFIED
1. MATERIAL: BT RESIN CCL-HL832 WITH TAIYO PSR4000 AUS5 SOLDER MASK.
  2. PLATING: Cu 15 TO 20 MICROMETERS  
Ni 10 ± 5 MICROMETERS  
Au 1 ± 0.5 MICROMETER
  3. REFERENCE JEDEC MO-208, VARIATION NNEB, DATED DECEMBER 1999.

APPROVALS	DATE	 National Semiconductor 2900 Semiconductor Dr., Santa Clara, CA 95052-8090	<b>CSP, PLASTIC, LAMINATED,</b> <b>9 x 9 x 1 mm BODY,</b> <b>112 L, 0.5 mm PITCH</b>		
DRAWN T. LEQUANG	01/27/2000				
DFTG. CHK. MARTA SUCHY	01/27/2000				
ENGR. CHK. GLENN NARVAEZ	02/27/2000				
 INCH [MM]		SCALE	SIZE	DRAWING NUMBER	REV
		N/A	C	(SC)MKT-SLB112A	A
		FORMERLY: N/A	SHEET 1 of 1		